PCA9517

Level translating I²C-bus repeater

Rev. 03 — 30 January 2007 Product data sheet

1. General description

The PCA9517 is a CMOS integrated circuit that provides level shifting between low voltage (down to 0.9 V) and higher voltage (2.7 V to 5.5 V) I²C-bus or SMBus applications. While retaining all the operating modes and features of the I²C-bus system during the level shifts, it also permits extension of the I²C-bus by providing bidirectional buffering for both the data (SDA) and the clock (SCL) lines, thus enabling two buses of 400 pF. Using the PCA9517 enables the system designer to isolate two halves of a bus for both voltage and capacitance. The SDA and SCL pins are over voltage tolerant and are high-impedance when the PCA9517 is unpowered.

The 2.7 V to 5.5 V bus B-side drivers behave much like the drivers on the PCA9515A device, while the adjustable voltage bus A-side drivers drive more current and eliminate the static offset voltage. This results in a LOW on the B-side translating into a nearly 0 V LOW on the A-side which accommodates smaller voltage swings of lower voltage logic.

The static offset design of the B-side PCA9517 I/O drivers prevent them from being connected to another device that has rise time accelerator including the PCA9510, PCA9511, PCA9512, PCA9513, PCA9514, PCA9515A, PCA9516A, PCA9517 (B-side), or PCA9518. The A-side of two or more PCA9517s can be connected together, however, to allow a star topography with the A-side on the common bus, and the A-side can be connected directly to any other buffer with static or dynamic offset voltage. Multiple PCA9517s can be connected in series, A-side to B-side, with no build-up in offset voltage with only time of flight delays to consider.

The PCA9517 drivers are not enabled unless V_{CCA} is above 0.8 V and V_{CC} is above 2.5 V. The EN pin can also be used to turn the drivers on and off under system control. Caution should be observed to only change the state of the enable pin when the bus is idle.

The output pull-down on the B-side internal buffer LOW is set for approximately 0.5 V, while the input threshold of the internal buffer is set about 70 mV lower (0.43 V). When the B-side I/O is driven LOW internally, the LOW is not recognized as a LOW by the input. This prevents a lock-up condition from occurring. The output pull-down on the A-side drives a hard LOW and the input level is set at $0.3V_{CCA}$ to accommodate the need for a lower LOW level in systems where the low voltage side supply voltage is as low as 0.9 V.

2. Features

- 2 channel, bidirectional buffer isolates capacitance and allows 400 pF on either side of the device
- Voltage level translation from 0.9 V to 5.5 V and from 2.7 V to 5.5 V
- Footprint and functional replacement for PCA9515/15A
- I²C-bus and SMBus compatible

founded by Philips

- Active HIGH repeater enable input
- Open-drain input/outputs
- Lock-up free operation
- Supports arbitration and clock stretching across the repeater
- Accommodates Standard mode and Fast mode I²C-bus devices and multiple masters
- Powered-off high-impedance I²C-bus pins
- A-side operating supply voltage range of 0.9 V to 5.5 V
- B-side operating supply voltage range of 2.7 V to 5.5 V
- 5 V tolerant I²C-bus and enable pins
- 0 Hz to 400 kHz clock frequency (the maximum system operating frequency may be less than 400 kHz because of the delays added by the repeater).
- ESD protection exceeds 2000 V HBM per JESD22-A114, 150 V MM per JESD22-A115, and 1000 V CDM per JESD22-C101
- Latch-up testing is done to JEDEC Standard JESD78 which exceeds 100 mA
- Packages offered: SO8 and TSSOP8

3. Ordering information

Table 1. Ordering information

T_{amb} = −40 °C to +85 °C

Type number	Topside mark	Package		
		Name	Description	Version
PCA9517D	PCA9517	SO8	plastic small outline package; 8 leads; body width 3.9 mm	SOT96-1
PCA9517DP	9517	TSSOP8[1]	plastic thin shrink small outline package; 8 leads; body width 3 mm	SOT505-1

[1] Also known as MSOP8

4. Functional diagram

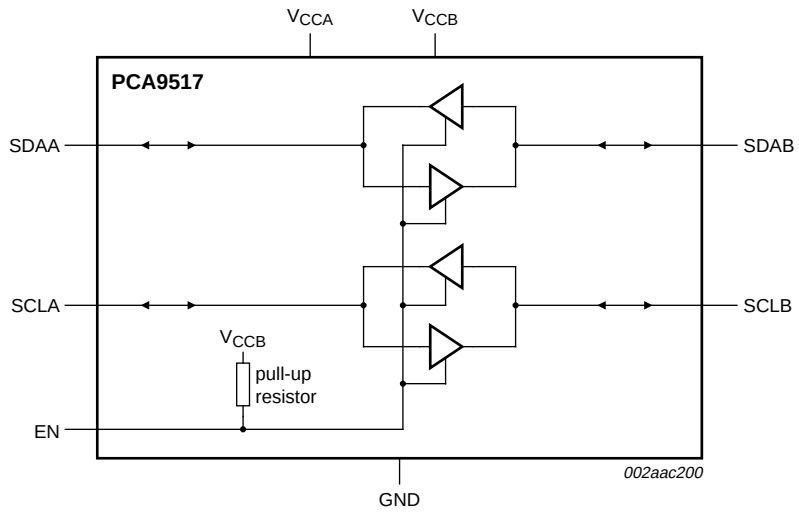


Fig 1. Functional diagram of PCA9517

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5. Pinning information

5.1 Pinning

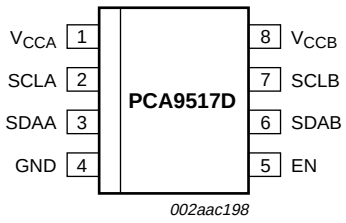


Fig 2. Pin configuration for SO8

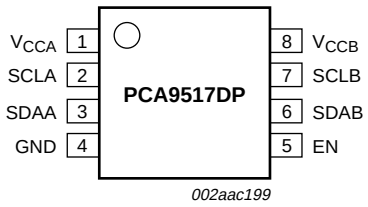


Fig 3. Pin configuration for TSSOP8 (MSOP8)

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
V_{CCA}	1	A-side supply voltage (0.9 V to 5.5 V)
SCLA	2	serial clock A-side bus
SDAA	3	serial data A-side bus
GND	4	supply ground (0 V)
EN	5	active HIGH repeater enable input
SDAB	6	serial data B-side bus
SCLB	7	serial clock B-side bus
V_{CCB}	8	B-side supply voltage (2.7 V to 5.5 V)

6. Functional description

Refer to Figure 1 “Functional diagram of PCA9517”.

The PCA9517 enables I²C-bus or SMBus translation down to V_{CCA} as low as 0.9 V without degradation of system performance. The PCA9517 contains two bidirectional open-drain buffers specifically designed to support up-translation/down-translation between the low voltage (as low as 0.9 V) and a 3.3 V or 5 V I²C-bus or SMBus. All inputs and I/Os are overvoltage tolerant to 5.5 V even when the device is unpowered (V_{CCB} and/or V_{CCA} = 0 V). The PCA9517 includes a power-up circuit that keeps the output drivers turned off until V_{CCB} is above 2.5 V and the V_{CCA} is above 0.8 V. V_{CCB} and V_{CCA} can be applied in any sequence at power-up. After power-up and with the enable (EN) HIGH, a LOW level on the A-side (below $0.3V_{CCA}$) turns the corresponding B-side driver (either SDA or SCL) on and drives the B-side down to about 0.5 V. When the A-side rises above $0.3V_{CCA}$ the B-side pull-down driver is turned off and the external pull-up resistor pulls the pin HIGH. When the B-side falls first and goes below $0.3V_{CCB}$ the A-side driver is turned on and the A-side pulls down to 0 V. The B-side pull-down is not enabled unless the B-side voltage goes below 0.4 V. If the B-side low voltage does not go below 0.5 V, the A-side driver will turn off when the B-side voltage is above $0.7V_{CCB}$. If the B-side low voltage goes below 0.4 V, the B-side pull-down driver is enabled and the B-side will only

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be able to rise to 0.5 V until the A-side rises above $0.3V_{CCA}$, then the B-side will continue to rise being pulled up by the external pull-up resistor. The V_{CCA} is only used to provide the $0.3V_{CCA}$ reference to the A-side input comparators and for the power good detect circuit. The PCA9517 logic and all I/Os are powered by the V_{CCB} pin.

6.1 Enable

The EN pin is active HIGH with an internal pull-up to V_{CCB} and allows the user to select when the repeater is active. This can be used to isolate a badly behaved slave on power-up until after the system power-up reset. It should never change state during an I²C-bus operation because disabling during a bus operation will hang the bus and enabling part way through a bus cycle could confuse the I²C-bus parts being enabled.

The enable pin should only change state when the global bus and the repeater port are in an idle state to prevent system failures.

6.2 I²C-bus systems

As with the standard I²C-bus system, pull-up resistors are required to provide the logic HIGH levels on the buffered bus (standard open-collector configuration of the I²C-bus). The size of these pull-up resistors depends on the system, but each side of the repeater must have a pull-up resistor. This part designed to work with Standard mode and Fast mode I²C-bus devices in addition to SMBus devices. Standard mode I²C-bus devices only specify 3 mA output drive; this limits the termination current to 3 mA in a generic I²C-bus system where Standard mode devices and multiple masters are possible. Under certain conditions higher termination currents can be used.

Please see Application Note *AN255, I²C/SMBus Repeaters, Hubs and Expanders* for additional information on sizing resistors and precautions when using more than one PCA9517 in a system or using the PCA9517 in conjunction with other bus buffers.

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7. Application design-in information

A typical application is shown in Figure 4. In this example, the system master is running on a 3.3 V I²C-bus while the slave is connected to a 1.2 V bus. Both buses run at 400 kHz. Master devices can be placed on either bus.

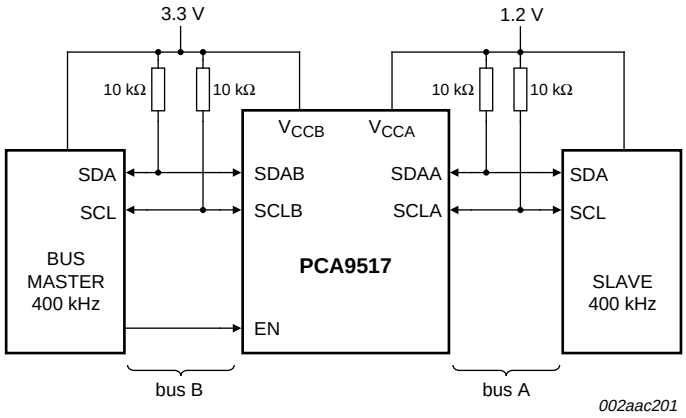


Fig 4. Typical application

The PCA9517 is 5 V tolerant, so it does not require any additional circuitry to translate between 0.9 V to 5.5 V bus voltages and 2.7 V to 5.5 V bus voltages.

When the A-side of the PCA9517 is pulled LOW by a driver on the I²C-bus, a comparator detects the falling edge when it goes below $0.3V_{CCA}$ and causes the internal driver on the B-side to turn on, causing the B-side to pull down to about 0.5 V. When the B-side of the PCA9517 falls, first a CMOS hysteresis type input detects the falling edge and causes the internal driver on the A-side to turn on and pull the A-side pin down to ground. In order to illustrate what would be seen in a typical application, refer to Figure 8 and Figure 9. If the bus master in Figure 4 were to write to the slave through the PCA9517, waveforms shown in Figure 8 would be observed on the A bus. This looks like a normal I²C-bus transmission except that the HIGH level may be as low as 0.9 V, and the turn on and turn off of the acknowledge signals are slightly delayed.

On the B bus side of the PCA9517, the clock and data lines would have a positive offset from ground equal to the V_{OL} of the PCA9517. After the 8th clock pulse, the data line will be pulled to the V_{OL} of the slave device which is very close to ground in this example. At the end of the acknowledge, the level rises only to the LOW level set by the driver in the PCA9517 for a short delay while the A bus side rises above $0.3V_{CCA}$ then it continues HIGH. It is important to note that any arbitration or clock stretching events require that the LOW level on the B bus side at the input of the PCA9517 (V_{IL}) be at or below 0.4 V to be recognized by the PCA9517 and then transmitted to the A bus side.

Multiple PCA9517 A-sides can be connected in a star configuration (Figure 5), allowing all nodes to communicate with each other.

Multiple PCA9517s can be connected in series (Figure 6) as long as the A-side is connected to the B-side. I²C-bus slave devices can be connected to any of the bus segments. The number of devices that can be connected in series is limited by repeater delay/time-of-flight considerations on the maximum bus speed requirements.

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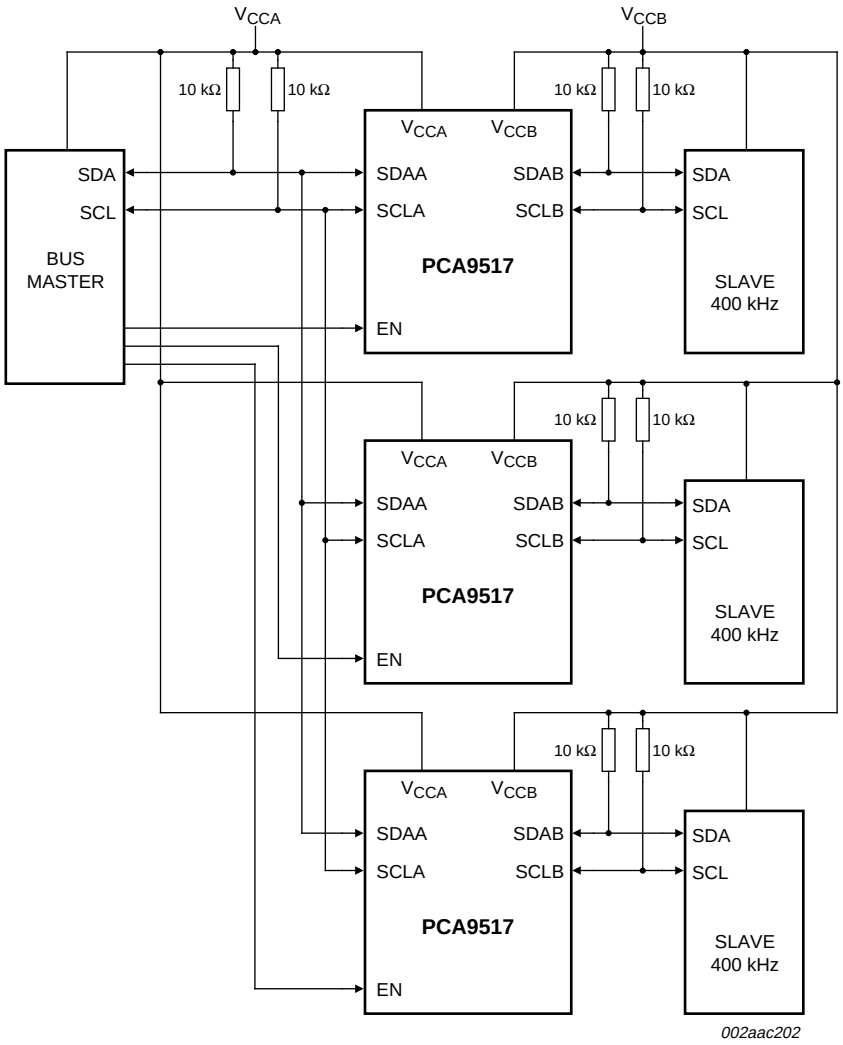


Fig 5. Typical star application

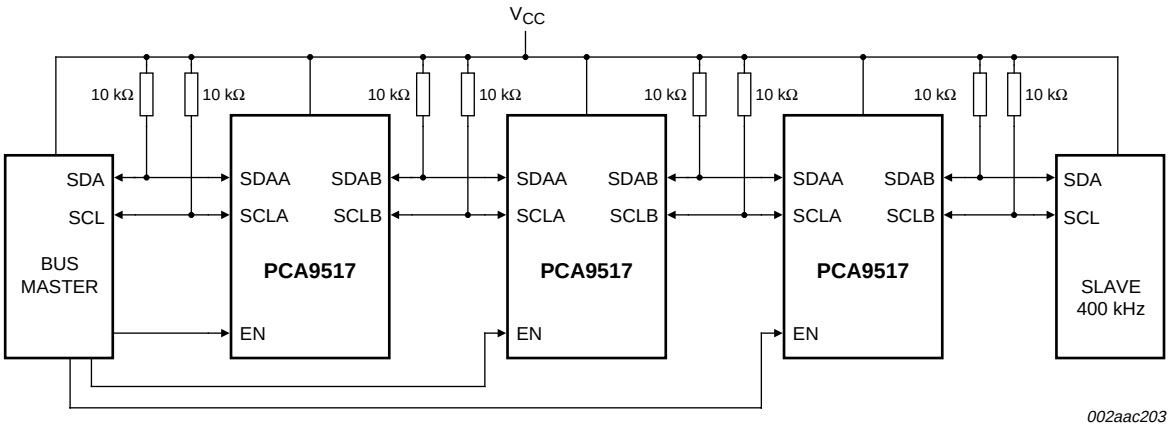


Fig 6. Typical series application

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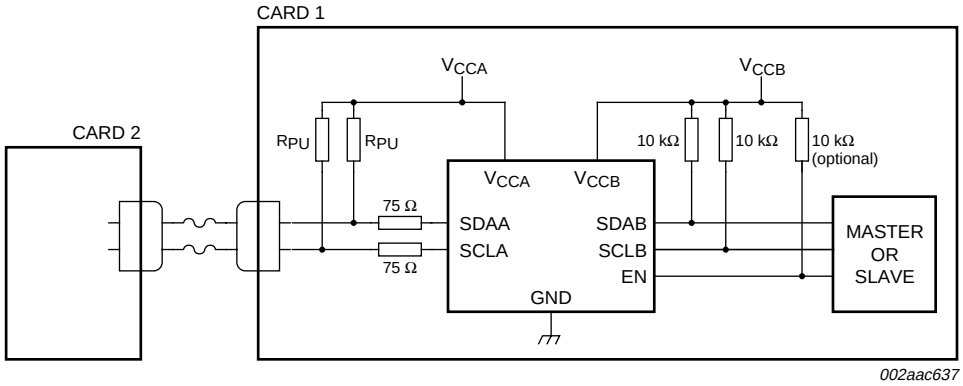


Fig 7. Typical application of PCA9517 driving a short cable

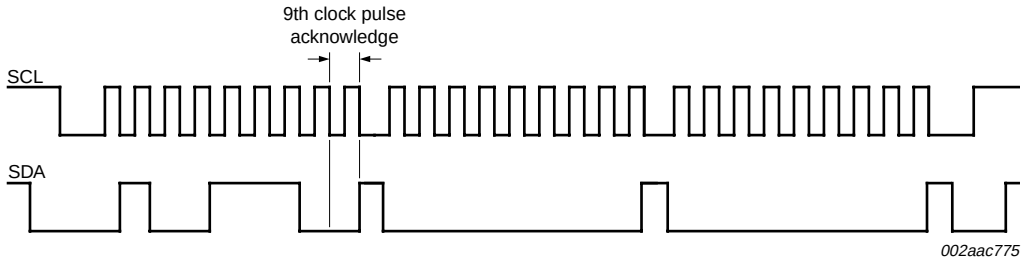


Fig 8. Bus A (0.9 V to 5.5 V bus) waveform

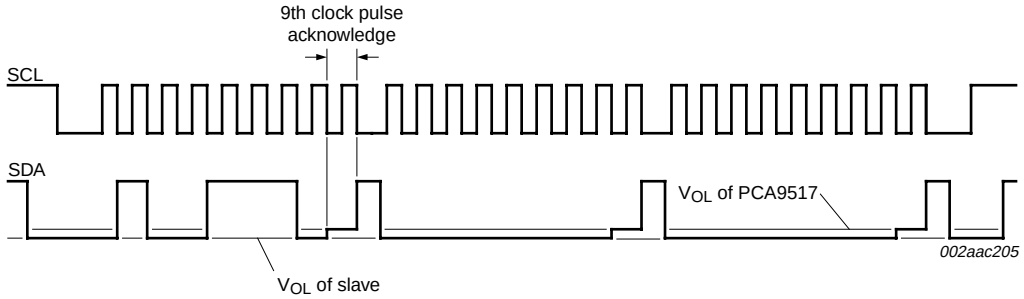


Fig 9. Bus B (2.7 V to 5.5 V) waveform

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8. Limiting values

Table 3. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CCB}	supply voltage, B-side bus	2.7 V to 5.5 V	–0.5	+7	V
V_{CCA}	supply voltage, A-side bus	adjustable	–0.5	+7	V
V_{bus}	voltage on I²C-bus B-side, or enable (EN)		–0.5	+7	V
I	DC current	any pin	-	50	mA
P_{tot}	total power dissipation		-	100	mW
T_{stg}	storage temperature		–55	+125	°C
T_{amb}	ambient temperature	operating in free air	–40	+85	°C
T_j	junction temperature		-	+125	°C

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9. Static characteristics

Table 4. Static characteristics

V_{CC} = 2.7 V to 5.5 V; GND = 0 V; T_{amb} = −40 °C to +85 °C; unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Supplies							
V_{CCB}	supply voltage, B-side bus			2.7	-	5.5	V
V_{CCA}	supply voltage, A-side bus		[1]	0.9	-	5.5	V
$I_{CC(VCCA)}$	supply current on pin V_{CCA}			-	-	1	mA
I_{CCH}	HIGH-state supply current	both channels HIGH; V_{CC} = 5.5 V; SDAn = SCLn = V_{CC}		-	1.5	5	mA
I_{CCL}	LOW-state supply current	both channels LOW; V_{CC} = 5.5 V; one SDA and one SCL = GND; other SDA and SCL open		-	1.5	5	mA
I_{CCAc}	quiescent supply current in contention	V_{CC} = 5.5 V; SDAn = SCLn = V_{CC}		-	1.5	5	mA
Input and output SDAB and SCLB							
V_{IH}	HIGH-level input voltage			$0.7V_{CCB}$	-	5.5	V
V_{IL}	LOW-level input voltage		[2]	−0.5	-	$+0.3V_{CCB}$	V
V_{ILc}	LOW-level input voltage contention			−0.5	0.4	-	V
V_{IK}	input clamping voltage	I_I = −18 mA		-	-	−1.2	V
I_{LI}	input leakage current	V_I = 3.6 V		-	-	±1	µA
I_{IL}	LOW-level input current	SDA, SCL; V_I = 0.2 V		-	-	10	µA
V_{OL}	LOW-level output voltage	I_{OL} = 100 µA or 6 mA		0.47	0.52	0.6	V
V_{OL}–V_{ILc}	LOW-level input voltage below output LOW-level voltage	guaranteed by design		-	-	70	mV
I_{LOH}	HIGH-level output leakage current	V_O = 3.6 V		-	-	10	µA
C_{io}	input/output capacitance	V_I = 3 V or 0 V; V_{CC} = 3.3 V		-	6	7	pF
		V_I = 3 V or 0 V; V_{CC} = 0 V		-	6	7	pF
Input and output SDAA and SCLA							
V_{IH}	HIGH-level input voltage			$0.7V_{CCA}$	-	5.5	V
V_{IL}	LOW-level input voltage		[3]	−0.5	-	$+0.3V_{CCA}$	V
V_{IK}	input clamping voltage	I_I = −18 mA		-	-	−1.2	V
I_{LI}	input leakage current	V_I = 3.6 V		-	-	±1	µA
I_{IL}	LOW-level input current	SDA, SCL; V_I = 0.2 V		-	-	10	µA
V_{OL}	LOW-level output voltage	I_{OL} = 6 mA		-	0.1	0.2	V
I_{LOH}	HIGH-level output leakage current	V_O = 3.6 V		-	-	10	µA
C_{io}	input/output capacitance	V_I = 3 V or 0 V; V_{CC} = 3.3 V		-	6	7	pF
		V_I = 3 V or 0 V; V_{CC} = 0 V		-	6	7	pF

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Table 4. Static characteristics *…continued*

V_{CC} = 2.7 V to 5.5 V; GND = 0 V; T_{amb} = −40 °C to +85 °C; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Enable						
V_{IL}	LOW-level input voltage		−0.5	-	$+0.3V_{CCB}$	V
V_{IH}	HIGH-level input voltage		$0.7V_{CCB}$	-	5.5	V
$I_{IL(EN)}$	LOW-level input current on pin EN	V_I = 0.2 V, EN; V_{CC} = 3.6 V	-	−10	−30	µA
I_{LI}	input leakage current		−1	-	+1	µA
C_i	input capacitance	V_I = 3.0 V or 0 V	-	6	7	pF

[1] LOW-level supply voltage.

[2] V_{IL} specification is for the first LOW level seen by the SDAB/SCLB lines. V_{ILc} is for the second and subsequent LOW levels seen by the SDAB/SCLB lines.

[3] V_{IL} for A-side with envelope noise must be below $0.3V_{CCA}$ for stable performance.

10. Dynamic characteristics

Table 5. Dynamic characteristics

V_{CC} = 2.7 V to 5.5 V; GND = 0 V; T_{amb} = −40 °C to +85 °C; unless otherwise specified.[1][2]

Symbol	Parameter	Conditions		Min	Typ[3]	Max	Unit
t_{PLH}	LOW-to-HIGH propagation delay	B-side to A-side; Figure 12	[4]	100	170	250	ns
t_{PHL}	HIGH-to-LOW propagation delay	B-side to A-side; Figure 10					
		$V_{CCA} \leq 2.7$ V	[5]	30	80	110	ns
		$V_{CCA} \geq 3$ V		10	66	300	ns
$t_{t(LH)}$	LOW-to-HIGH transition time	A-side; Figure 10		10	20	30	ns
$t_{t(HL)}$	HIGH-to-LOW transition time	A-side; Figure 10					
		$V_{CCA} \leq 2.7$ V	[5]	1	77	105	ns
		$V_{CCA} \geq 3$ V		20	70	175	ns
t_{PLH}	LOW-to-HIGH propagation delay	A-side to B-side; Figure 11	[6]	25	53	110	ns
t_{PHL}	HIGH-to-LOW propagation delay	A-side to B-side; Figure 11	[6]	60	79	230	ns
$t_{t(LH)}$	LOW-to-HIGH transition time	B-side; Figure 11		120	140	170	ns
$t_{t(HL)}$	HIGH-to-LOW transition time	B-side; Figure 11		30	48	90	ns
t_{su}	set-up time	EN HIGH before START condition	[7]	100	-	-	ns
t_h	hold time	EN HIGH after STOP condition	[7]	100	-	-	ns

[1] Times are specified with loads of 1.35 kΩ pull-up resistance and 57 pF load capacitance on the B-side, and 167 Ω pull-up resistance and 57 pF load capacitance on the A-side. Different load resistance and capacitance will alter the RC time constant, thereby changing the propagation delay and transition times.

[2] Pull-up voltages are V_{CCA} on the A-side and V_{CCB} on the B-side.

[3] Typical values were measured with V_{CCA} = 3.3 V at T_{amb} = 25 °C, unless otherwise noted.

[4] The t_{PLH} delay data from B-side to A-side is measured at 0.5 V on the B-side to $0.5V_{CCA}$ on the A-side when V_{CCA} is less than 2 V, and 1.5 V on the A-side if V_{CCA} is greater than 2 V.

[5] Typical value measured with V_{CCA} = 2.7 V at T_{amb} = 25 °C.

[6] The proportional delay data from A-side to B-side is measured at $0.3V_{CCA}$ on the A-side to 1.5 V on the B-side.

[7] The enable pin, EN, should only change state when the global bus and the repeater port are in an idle state.

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10.1 AC waveforms

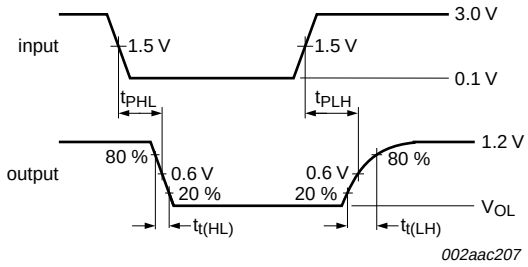


Fig 10. Propagation delay and transition times; B-side to A-side

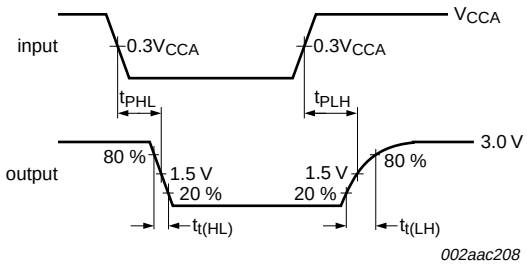


Fig 11. Propagation delay and transition times; A-side to B-side

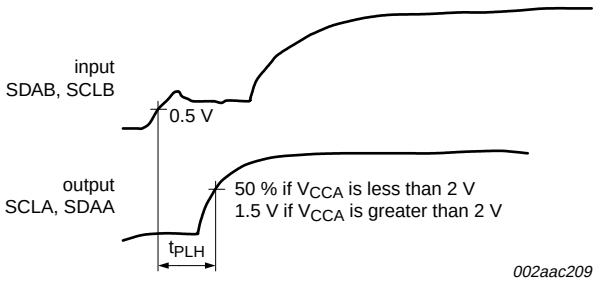
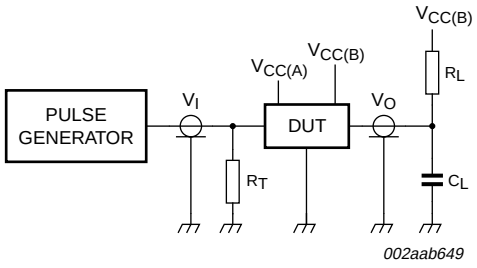


Fig 12. Propagation delay

11. Test information



R_L = load resistor; 1.35 kΩ on B-side; 167 Ω on A-side (0.9 V to 2.7 V) and 450 Ω on A-side (3.0 V to 5.5 V).

C_L = load capacitance includes jig and probe capacitance; 57 pF

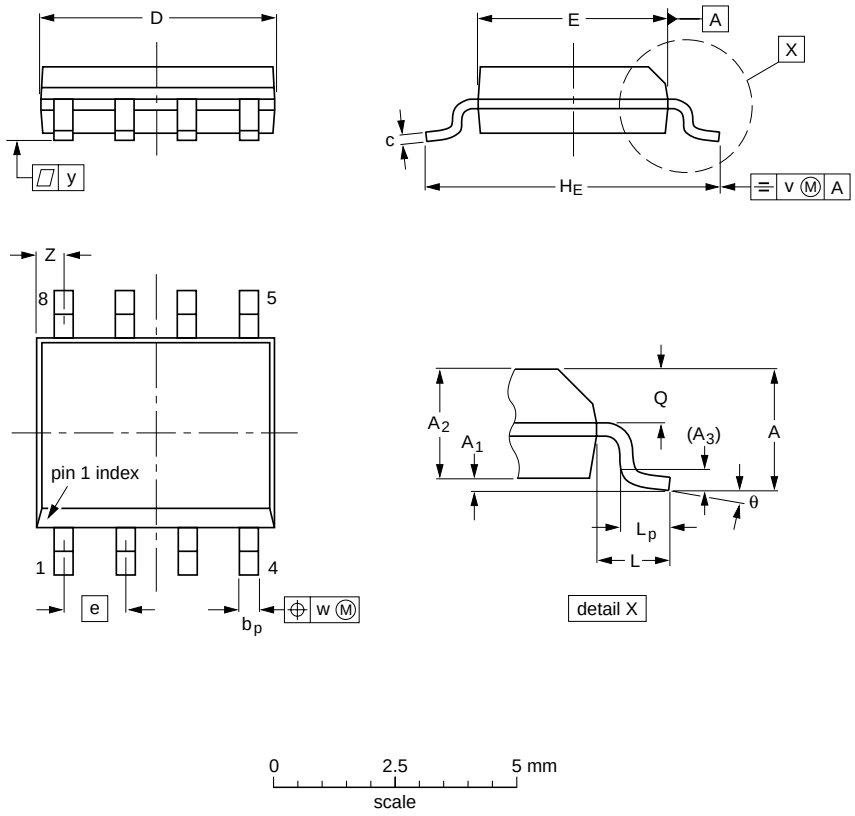
R_T = termination resistance should be equal to Z_o of pulse generators

Fig 13. Test circuit for open-drain outputs

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12. Package outline

SO8: plastic small outline package; 8 leads; body width 3.9 mm **SOT96-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	5.0 4.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8^o 0^o
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.20 0.19	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

Notes

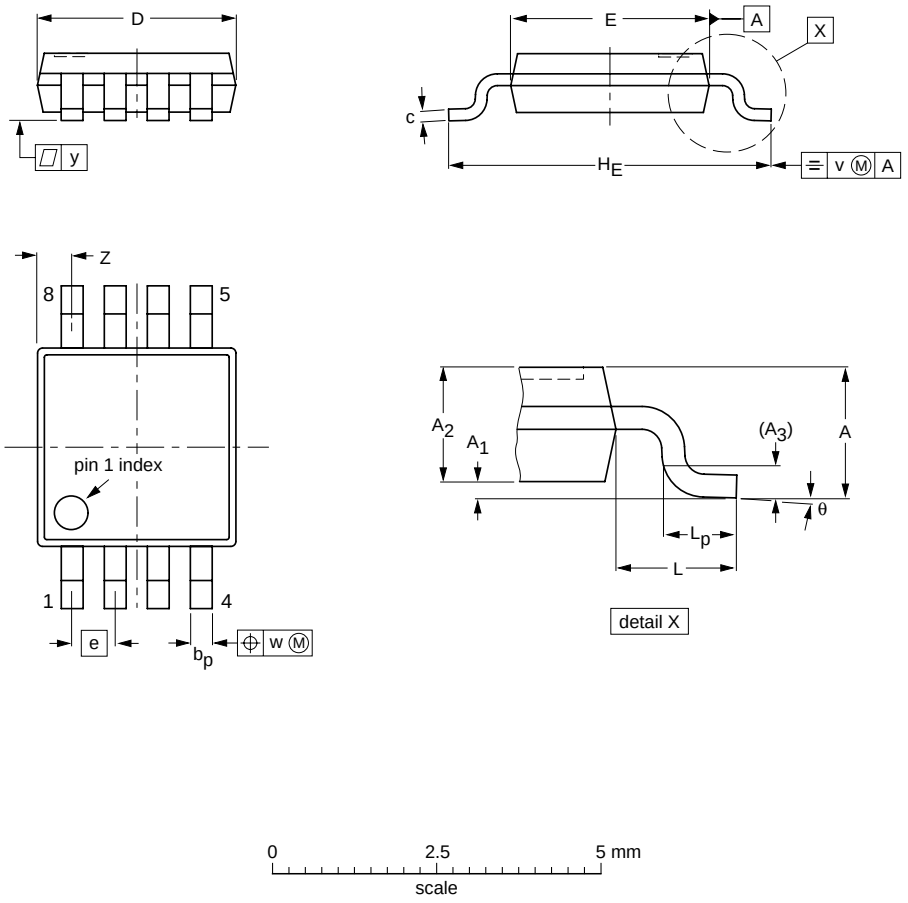
1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT96-1	076E03	MS-012				~~99-12-27~~ 03-02-18

Fig 14. Package outline SOT96-1 (SO8)

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TSSOP8: plastic thin shrink small outline package; 8 leads; body width 3 mm **SOT505-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	v	w	y	$Z^{(1)}$	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.45 0.25	0.28 0.15	3.1 2.9	3.1 2.9	0.65	5.1 4.7	0.94	0.7 0.4	0.1	0.1	0.1	0.70 0.35	6° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT505-1						~~99-04-09~~ 03-02-18

Fig 15. Package outline SOT505-1 (TSSOP8)

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13. Soldering

This text provides a very brief insight into a complex technology. A more in-depth account of soldering ICs can be found in Application Note *AN10365 "Surface mount reflow soldering description"*.

13.1 Introduction to soldering

Soldering is one of the most common methods through which packages are attached to Printed Circuit Boards (PCBs), to form electrical circuits. The soldered joint provides both the mechanical and the electrical connection. There is no single soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and Surface Mount Devices (SMDs) are mixed on one printed wiring board; however, it is not suitable for fine pitch SMDs. Reflow soldering is ideal for the small pitches and high densities that come with increased miniaturization.

13.2 Wave and reflow soldering

Wave soldering is a joining technology in which the joints are made by solder coming from a standing wave of liquid solder. The wave soldering process is suitable for the following:

- Through-hole components
- Leaded or leadless SMDs, which are glued to the surface of the printed circuit board

Not all SMDs can be wave soldered. Packages with solder balls, and some leadless packages which have solder lands underneath the body, cannot be wave soldered. Also, leaded SMDs with leads having a pitch smaller than ~0.6 mm cannot be wave soldered, due to an increased probability of bridging.

The reflow soldering process involves applying solder paste to a board, followed by component placement and exposure to a temperature profile. Leaded packages, packages with solder balls, and leadless packages are all reflow solderable.

Key characteristics in both wave and reflow soldering are:

- Board specifications, including the board finish, solder masks and vias
- Package footprints, including solder thieves and orientation
- The moisture sensitivity level of the packages
- Package placement
- Inspection and repair
- Lead-free soldering versus PbSn soldering

13.3 Wave soldering

Key characteristics in wave soldering are:

- Process issues, such as application of adhesive and flux, clinching of leads, board transport, the solder wave parameters, and the time during which components are exposed to the wave
- Solder bath specifications, including temperature and impurities

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13.4 Reflow soldering

Key characteristics in reflow soldering are:

- Lead-free versus SnPb soldering; note that a lead-free reflow process usually leads to higher minimum peak temperatures (see Figure 16) than a PbSn process, thus reducing the process window
- Solder paste printing issues including smearing, release, and adjusting the process window for a mix of large and small components on one board
- Reflow temperature profile; this profile includes preheat, reflow (in which the board is heated to the peak temperature) and cooling down. It is imperative that the peak temperature is high enough for the solder to make reliable solder joints (a solder paste characteristic). In addition, the peak temperature must be low enough that the packages and/or boards are not damaged. The peak temperature of the package depends on package thickness and volume and is classified in accordance with Table 6 and 7

Table 6. SnPb eutectic process (from J-STD-020C)

Package thickness (mm)	Package reflow temperature (°C)	
	Volume (mm³)	
	< 350	≥ 350
< 2.5	235	220
≥ 2.5	220	220

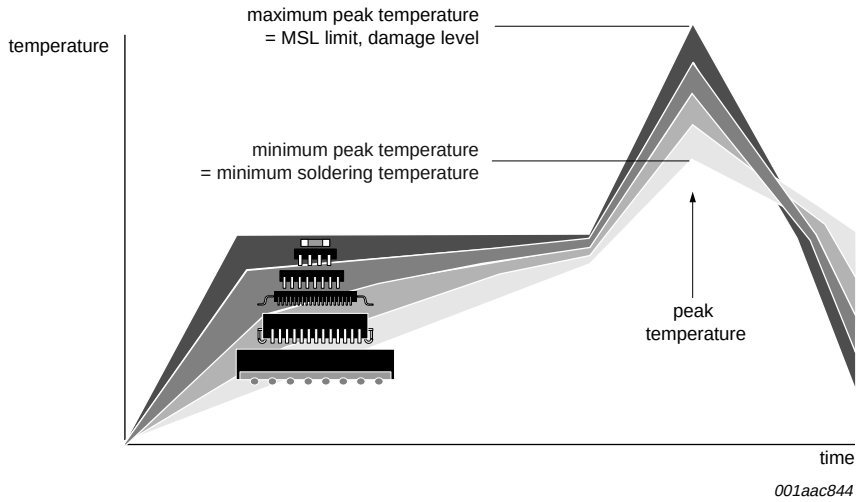
Table 7. Lead-free process (from J-STD-020C)

Package thickness (mm)	Package reflow temperature (°C)		
	Volume (mm³)		
	< 350	350 to 2000	> 2000
< 1.6	260	260	260
1.6 to 2.5	260	250	245
> 2.5	250	245	245

Moisture sensitivity precautions, as indicated on the packing, must be respected at all times.

Studies have shown that small packages reach higher temperatures during reflow soldering, see Figure 16.

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MSL: Moisture Sensitivity Level

Fig 16. Temperature profiles for large and small components

For further information on temperature profiles, refer to Application Note *AN10365 "Surface mount reflow soldering description"*.

14. Abbreviations

Table 8. Abbreviations

Acronym	Description
CDM	Charged Device Model
CMOS	Complementary Metal Oxide Silicon
ESD	ElectroStatic Discharge
HBM	Human Body Model
I²C-bus	Inter Integrated Circuit bus
MM	Machine Model
SMBus	System Management Bus

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15. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PCA9517_3	20070130	Product data sheet	-	PCA9517_2
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Section 2 “Features”, 15th bullet item: changed “200 V MM per JESD22-A115” to “150 V MM per JESD22-A115” • Table 4 “Static characteristics” added new Table note 3, and its reference in sub-section “Input and output SDAA and SCLA”, symbol V_{IL}. • added (new) Figure 7 “Typical application of PCA9517 driving a short cable” • Figure 8 “Bus A (0.9 V to 5.5 V bus) waveform”: SDA signal modified • Figure 9 “Bus B (2.7 V to 5.5 V) waveform”: SDA signal modified • Table 5 “Dynamic characteristics”: – $t_{t(LH)}$, A-side: changed reference to timing diagram from Figure 11 to Figure 10 – $t_{t(HL)}$, A-side: changed reference to timing diagram from Figure 11 to Figure 10 – $t_{t(LH)}$, B-side: changed reference to timing diagram from Figure 10 to Figure 11 – $t_{t(HL)}$, B-side: changed reference to timing diagram from Figure 10 to Figure 11			
PCA9517_2 (9397 750 14918)	20060615	Product data sheet	-	PCA9517_1
PCA9517_1 (9397 750 13252)	20041005	Product data sheet	-	-

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16. Legal information

16.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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